

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Field Device Integration (FDI) –  
Part 6: FDI Technology Mapping**

**Intégration des appareils de terrain (FDI) –  
Partie 6: Mapping de technologies FDI**



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# CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope.....	7
2 Normative references .....	7
3 Terms, definitions, abbreviated terms, acronyms and conventions.....	7
3.1 Terms and definitions.....	7
3.2 Abbreviated terms and acronyms .....	8
3.3 Symbols.....	8
4 Technical concepts.....	8
4.1 General.....	8
4.1.1 Overview .....	8
4.1.2 Platforms.....	9
4.1.3 FDI Type Library.....	9
4.2 UIP representation.....	10
4.3 UIP executable representation .....	10
4.4 UIP executable compatibility rules .....	11
4.5 Allowed .NET Common Language Run-time version.....	11
4.5.1 General .....	11
4.5.2 CLR compatibility strategy .....	11
4.5.3 How to identify the .NET target platform of a UIP.....	12
4.6 Installing UIP .....	12
4.7 UIP Lifecycle.....	13
4.7.1 General .....	13
4.7.2 UIP Assembly activation steps.....	13
4.7.3 UIP Assembly deactivation steps .....	15
4.8 Interaction between an FDI Client and a UIP.....	16
4.8.1 Handling of standard UI elements .....	16
4.8.2 Non-blocking service execution .....	16
4.8.3 Blocking service execution.....	17
4.8.4 Cancel service execution .....	18
4.8.5 Threading .....	19
4.8.6 Timeout .....	19
4.8.7 Exception handling .....	20
4.8.8 Type safe interfaces .....	21
4.8.9 Globalization and localization .....	21
4.8.10 WPF Control handling.....	21
4.8.11 Win Form handling.....	21
4.9 Security .....	21
4.9.1 General .....	21
4.9.2 Access permissions .....	22
4.9.3 Code identity concept .....	23
5 Interface definition.....	23
Bibliography.....	27
Figure 1 – FDI Type Library structure.....	10

Figure 2 – .NET surrogate process ..... 12

Figure 3 – Identification of Run-time Version..... 12

Figure 4 – IAsyncPattern based asynchronous service execution example..... 17

Figure 5 – Blocking service execution example using IAsyncResult based pattern ..... 18

Figure 6 – Cancel service processing sequence example ..... 18

Figure 7 – Exception source ..... 20

  

Table 1 – Technology edition reference ..... 9

Table 2 – Base Property Services ..... 24

Table 3 – Device Model Services ..... 24

Table 4 – Access Control Services..... 24

Table 5 – Direct Access Services ..... 24

Table 6 – Hosting Services ..... 25

Table 7 – UIP Services ..... 25

Table 8 – Base Data Types..... 26

Table 9 – Special Types ..... 26

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**FIELD DEVICE INTEGRATION (FDI) –**

**Part 6: FDI Technology Mapping**

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/349/CDV	65E/426/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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- b) Method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) Methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
- d) Extensible Device Object Model, see Patent Family US12/893,680.

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## FIELD DEVICE INTEGRATION (FDI) –

### Part 6: FDI Technology Mapping

#### 1 Scope

This part of IEC 62769 specifies the technology mapping for the concepts described in the Field Device Integration (FDI) standard. The technology mapping focuses on implementation regarding the components FDI Client and User Interface Plug-in (UIP) that are specific only to the workstation platform as defined in IEC 62769-4:2015, Annex E.

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62541 (all parts), *OPC Unified Architecture*

IEC 61804 (all parts), *Function blocks (FB) for process control*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

NOTE IEC 62769-1 is technically identical to FDI-2021.

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technically identical to FDI-2022.

NOTE 2 IEC 62769-2 is technically identical to FDI-2023.

IEC 62769-4:2015, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 1 IEC 62769-5 is technically identical to FDI-2025.

NOTE 2 IEC 62769-5 is technically identical to FDI-2027.

ISO/IEC 19505-1, *Information technology – Object Management Group Unified Modeling Language (OMG UML) – Part 1: Infrastructure*

ISO/IEC 29500, (all parts) *Information technology – Document description and processing languages – Office Open XML File Formats*

#### 3 Terms, definitions, abbreviated terms, acronyms and conventions

##### 3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1 as well as the following apply.